

Low Cost A/D Conversion Using COP800

National Semiconductor
Application Note 952
Robert Weiss
September 1994



INTRODUCTION

Many microcontroller applications require a low cost analog to digital conversion. In most cases the controller applications do not need high accuracy and short conversion time. This appnote describes a simple method for performing analog to digital conversion by reducing external elements and costs.

PRINCIPLE OF A/D CONVERSION

The principle of the single slope conversion technique is to measure the time it takes for the RC network to charge up to the threshold level on the port pin, by using Timer T1 in the input capture mode. The cycle count obtained in Timer T1 can be converted into voltage, either by direct calculation or by using a suitable approximation.

Figure 1 shows the block diagram for the simple A/D conversion which measures the temperature.

BASIC CIRCUIT IMPLEMENTATION

Usually most applications use a comparator to measure the time it takes for a RC network to charge up to the voltage level on the comparator input. To reduce cost, it is possible to switch both inputs as shown in Figure 2.

Port G3 is the Timer T1 input. Ports G2/G1 are general purpose I/O pins that can be configured using the I/O configurations (push-pull output/tristate). All Port G pins are Schmitt Trigger inputs. R_{LIM} is required to reduce the discharge current.

GENERAL IMPLEMENTATION

The temperature is measured with a NTC which is linearized with a parallel resistor. Using a parallel resistor, a linearization in the range of 100 Kelvin can be reached. The value of the resistor can be calculated as follow:

$$R_P = R_{tm} * (B - 2T_m) / (B + 2T_m)$$

R_{tm} Value of the NTC at a medium temperature
 T_m Medium Temperature
B NTC-material constant

The linearization reduces the code, improves the accuracy and the tolerance of the NTC-R network (e.g. NTC = $100 \text{ k}\Omega \pm 10\%$, $R = 12 \text{ k}\Omega \pm 1\%$, NTC//R $\pm 2\%$). Using that method the useful range does not cover the whole operating temperature range of the NTC.

GENERAL ACCURACY CONSIDERATIONS

Using a single slope A/D conversion the accuracy is dependent on the following parameters:

- Stability of the Clock frequency
- Time constant of the RC network
- Accuracy of the Schmitt Trigger level
- Non-linearity of the RC-network

Figure 3. The maximum failure that appears when a sawtooth is generated without using a current source. In the current application the maximum failure would be more than 15% without using methods for reducing the non-linearities of RC-network/NTC-network.

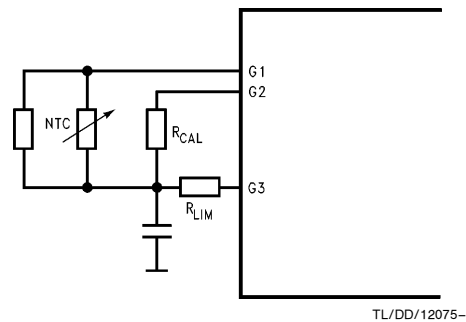


FIGURE 2. Basic Circuit Implementation

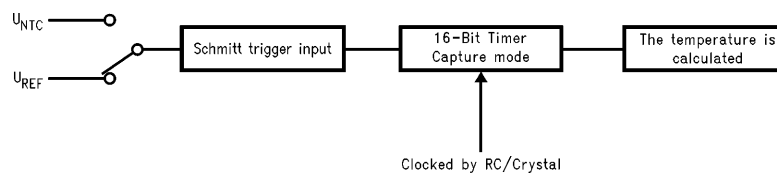
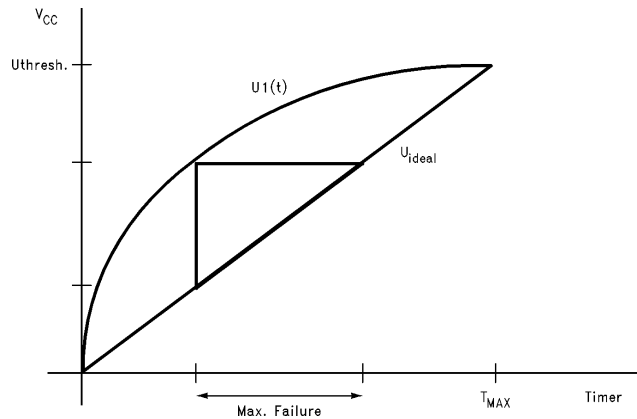


FIGURE 1. Simple A/D Conversion



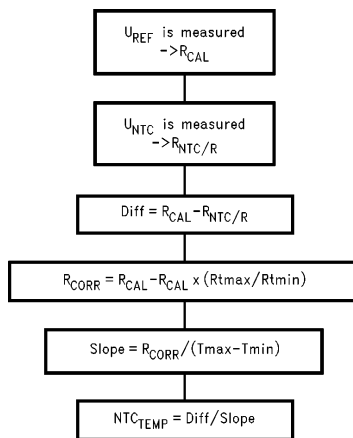
TL/DD/12075-3

FIGURE 3. Single Slope A/D Conversion

The maximum error occurs when the gradient of the exponential function (RC) equals the gradient of the straight line (counter).

To reduce the error that is caused by the non-linearity of the RC-network a offset should be added to the calculated value. The offset reduce the failure to the middle.

Further, the accuracy can be improved by using a relative measurement method. The following diagram shows the method.



TL/DD/12075-4

FIGURE 4. Accuracy Improvement

Measurement:

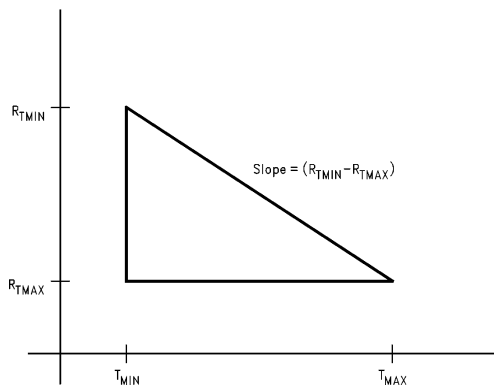
- Timer Capture mode: $R_{CAL} * C$ is measured
- Timer Capture mode: $R_{NTC}/R * C$ is measured

Calculation:

- Build the vertical-component ($R_{TMIN} - R_{TMAX}$) of the triangle
- Calculate the slope
- Calculate the actual temperature

Using this method the accuracy is primarily dependent on the accuracy of R_{TMIN} and R_{TMAX} and independent of the stability of the system clock, the capacitor and the threshold of the Schmitt Trigger level. The variation of the capacitor only leads to variation of the resolution.

The following diagram shows the ideal resistance/temperature characteristic of a NTC which is linearized with a parallel resistor.



TL/DD/12075-5

FIGURE 5. Resistance vs Temperature Characteristics

APPLICATION EXAMPLE

The following application example for temperature measurement demonstrates the procedure. The temperature is measured from 20° to 100° and is displayed on a Triplex LCD display.

$NTC_{20} = 100\text{ k}\Omega \pm 10\%$
 $R_P = 12\text{ k}\Omega \pm 1\%$
 $T_m = 333\text{ Kelvin} \rightarrow 60\text{ Degrees}$
 $B = 4800\text{ Kelvin}$
 $NTC_{20}/R_P = 10.7\text{ k}\Omega \pm 2\%$
 $R_{CAL} = 10.7\text{ k}\Omega \pm 1\%$
 $T_{MIN} = 20\text{ Degree}$
 $R_{TMIN} = 10.7\text{ k}\Omega$
 $T_{MAX} = 100\text{ Degree}$

$R_{TMAX} = 2.8\text{ k}\Omega$
 $C = 1\text{ }\mu\text{F}$
 $RC\text{-Clock} = 2\text{ MHz} \rightarrow 200\text{ kHz instruction cycle, } 5\text{ }\mu\text{s}$
 $\text{Timeconst.} = R_{CAL} * C \rightarrow 0.0107\text{s}$
 $\text{Resolution} = 2140 \rightarrow 11\text{ byte, depends which Cap. value is used}$

Accuracy = $\pm 2\text{ Degree}$

This temperature measurement example shows a low cost technique ideally suited for cost sensitive applications which do not need high accuracy.

Figure 6 shows the complete circuit of the demoboard using the Triplex LCD method and the low cost A/D conversion technique.

The Triplex LCD drive technique is documented in a separate application note.

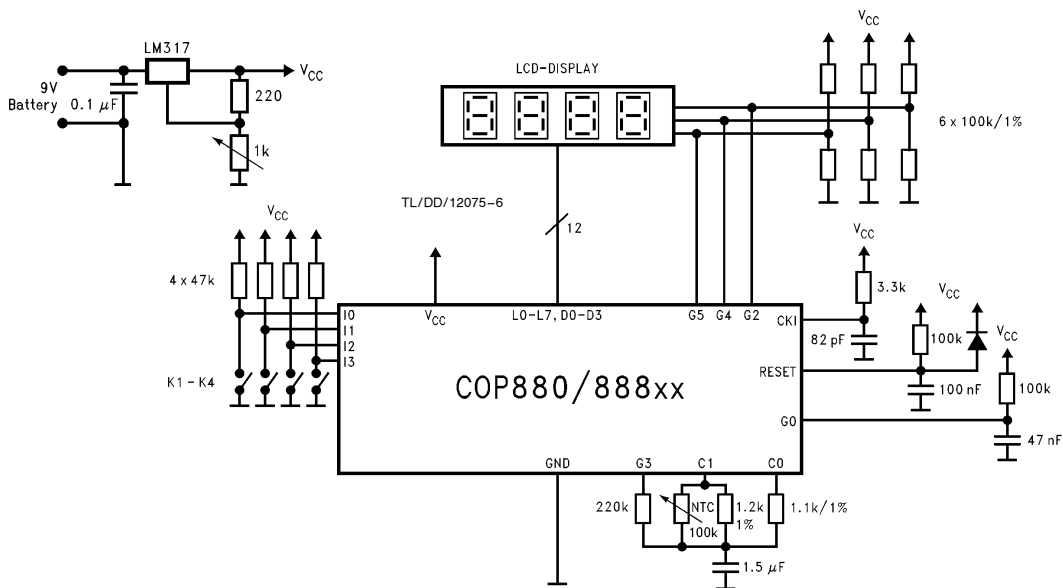


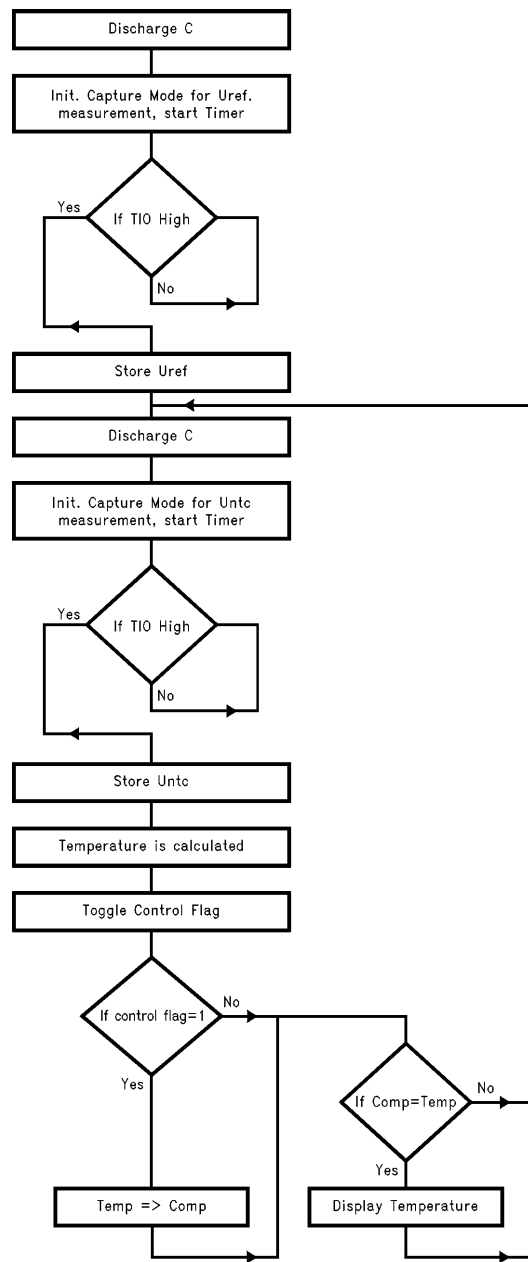
FIGURE 6. Circuit Diagram

Pressing key 1, key 2 the temperature is displayed in Degree/Fahrenheit.

Pressing key 3, key 4 Up/Down counter is displayed.

SOURCE CODE

Figure 7 shows the flow chart of the program.



TL/DD/12075-8

FIGURE 7. Flow Chart

The following code is required to implement the function. It does not include the code for the Triplex LCD drive.

```

RAM = 17 Byte;
ROM = 450 Byte; Optimization is possible about 50 byte if the B - pointer consistent is used!
;*****A/D-CONVERSION*****
;
;
;*****VAR. DECLARATION*****
.SECT REGPAGE,REG
COUNT1: .DSB 1
COUNT2: .DSB 1
;
.SECT BASEPAGE,BASE
ZL: .DSB 1 ;TEMPORARY
YL: .DSB 1 ;TEMPORARY
;
.SECT RAMPAGE,RAM
CALIBLO: .DSB 1 ;CALIBRATION-VALUE
CALIBHI: .DSB 1
NTCLO: .DSB 1 ;NTC-VALUE
NTCHI: .DSB 1
TEMP: .DSB 2 ;TEMP.-VALUE
KORRL: .DSB 2
COMPL: .DSB 1
COMPH: .DSB 1
CONTROL: .DSB 1 ;STATUS REGISTER
;*****START MAIN PROGRAM*****
MAIN: LD SP,#06F ;INIT SPACKPOINTER
      JSR DISCH ;DISCHARGE C (A/D-CONVERSION)
      JSR CALB ;INIT CAPTURE MODE FOR UREF. MEASURMENT
POLL: IFBIT 3,PORTGP ;POLL - MODE (TIO - PORT)
      JP CAL
      JP POLL
CAL: LD B,#CALIBLO
     JSR CAPTH ;STOP TIMER, STORE CAPTURE VALUE
     JSR CALCR ;SLOPE IS CALCULATED
NEW: JSR DISCH ;DISCHARGE C (A/D-CONVERSION)
     JSR NTC ;INIT CAPTURE MODEFOR UNTC MEASURMENT
POLL1: IFBIT 3,PORTGP ;POLL-MODE
      JP CAL1
      JP POLL1
CAL1: LD B,#NTCLO
     JSR CAPTH ;STOP TIMER, STORE CAPTURE VALUE
     JSR CALCN ;TEMPERATURE IS CALCULATED
     JSR DISCH ;DISCHARGE C (A/D-CONVERSION)
     JSR DCHECK ;REDUCE THE DISPLAY FLICKERING
     JMP NEW
.ENDSECT
;*****

```

TL/DD/12075-9

```

;*****
;
;SECT CODE1,ROM
;THIS ROUTINE IS REQUIRED TO REDUCE THE NOICE ON THE LINE AND THE
;DISPLAY FLICKERING.
;SECT CODE1,ROM
DCHECK:
    LD A,CONTROL    ;COMPARE TWO VALUES, IF EQUAL THEN
    XOR A,#080      ;DISPLAY IT, OTHERWISE THE OLD VALUE
    X A,CONTROL      ;IS DISPLAYED
    IFBIT 7,CONTROL
    JSR SAVE         ;TEMP. SAVE
    JSR COMP         ;COMPARE
    RET
;*****
; HANDLER FOR CAPTURE MODE
CAPTH: RBIT TPND,PSW ;RESET TIMER PENDING
    RBIT TRUN,PSW    ;STOP TIMER
    LD A,#0FF
    SC
    SUBC A,TAULO
    X A,[B+]         ;STORE THE CAPTURED VALUE
    LD A,#0FF
    SUBC A,TAUHI
    X A,[B+]         ;STORE THE CAPTURED VALUE
    RET
;*****
; CALIBRATION SUBROUTINE, UREF IS MEASURED
CALB:
    RBIT 3,PORTGD
    RBIT 3,PORTGC    ;TRISTATE TIO
    LD PORTCD,#00
    LD PORTCC,#00    ;TRISTATE PORT C
    TICAP HIGH       ;INIT CAPTURE MODE, HIGH SENSITIVE (MACRO)
    LD B,#CALIBLO
    SBIT 0,PORTCD    ;CONFIGURE C0 TO OUTPUT HIGH
    SBIT 0,PORTCC    ;CHARGE CAP.
    SBIT TRUN,CNTRL  ;START TIMER CAPTURE MODE
    RET
;*****
; NTC SUBROUTINE, UNTC IS MEASURED
NTC:
    RBIT 3,PORTGD
    RBIT 3,PORTGC    ;TRISTAT TIO
    LD PORTCD,#00
    LD PORTCC,#00    ;TRISTATE PORT C
    TICAP HIGH       ;INIT CAPTURE MODE. HIGH SENSITIVE (MACRO)
    LD B,#NTCLO
    SBIT 1,PORTCD    ;CONFIGURE C1 TO OUTPUT HIGH
    SBIT 1,PORTCC    ;CHARGE CAP.
    SBIT TRUN,CNTRL  ;START TIMER CAPTURE MODE
    RET
;*****

```

TL/DD/12075-10

```

;*****
;DISCHARGE - ROUTINE
DISCH:
    LD PORTCD,#000
    LD PORTCC,#000
    RBIT TIO,PORTGD ;DISCHARGE CAP.
    SBIT TIO,PORTGC
    LD COUNT1,#H(500) ;DISCHARGE TIME
    LD COUNT2,#L(500)
    JSR C1 ;DELAY ROUTINE FOR DISCHARGE TIME
    RET
;*****
;THIS SUBROUTINE CALCULATES THE SLOPE
;THE FOLLOWING CALCULATIONS ARE DONE
;KORR=CALIB/11KOHM (RCALIB.=11KOHM)
;KORR=KORR*2,8KOHM (T=100 DEGREE, RNTC=2,8KOHM)
;CALIB=CALIB-KORR
;DIV=CALIB\80 (TEMPRANGE=80 DEGREE,100-20), SLOPE IS CALCULATED
CALCR:
;KORR=CALIB/11KOHM
    LD ZL,#L(110)
    LD ZL+1,#H(110)
    LD A,CALIBLO
    X A,YL
    LD A,CALIBHI
    X A,YL+1
    JSR DIVBIN16 ;SUBROUTINE BINARY DIVIDE 16 BIT BY 16 BIT
    LD A,YL
    X A,KORRL
;*****
;KORR=KORR*28
    LD A,KORRL
    X A,ZL
    LD A,#28
    X A,YL
    JSR MULBIN8 ;SUBROUTINE MULTIPLY TWO 8 BIT VALUES
    LD A,YL
    X A,KORRL
    LD A,YL+1
    X A,KORRL+1
;*****
;KORR=CALIB-KORR
    LD B,#CALIBLO
    LD A,[B+]
    SC
    SUBC A,KORRL
    X A,KORRL
    LD A,[B]

```

TL/DD/12075-11

```

        SUBC A,KORRL+1
        X A,KORRL+1
;*****
;DIV=KORR/80
        LD ZL,#L(80)
        LD ZL+1,#H(80)
        LD A,KORRL
        X A,YL
        LD A,KORRL+1
        X A,YL+1
        JSR DIVBIN16      ;SUBROUTINE BINARY DIVIDE 16 BIT BY 16 BIT
        LD A,YL
        X A,DIV
        RET
;*****
;THIS SUBROUTINE CALCULATES THE TEMPERATURE
;THE FOLLOWING CALCULATIONS ARE DONE
;TEMP=CALIB-NTC
;TEMP=TEMP/DIV
;ADD OFFSET 20 DEGREE
;CONVERSION FROM HEX TO BCD
;*****
;TEMP=CALIB-NTC
CALCN: LD B,#CALIBLO
        LD A,[B+]
        SC
        SUBC A,NTCLO
        X A,TEMP
        LD A,[B]
        SUBC A,NTCHI
        IFNC
        JMP ERR
        X A,TEMP+1
;*****
;TEMP=TEMP/DIV
        LD A,TEMP
        X A,YL
        LD A,TEMP+1
        X A,YL+1
        LD A,DIV
        X A,ZL
        CLRA
        X A,ZL+1
        JSR DIVBIN16      ;SUBROUTINE BINARY DIVIDE 16 BIT BY 16 BIT
        LD A,YL
        ADD A,#20         ;ADD TEMPERATURE OFFSET
        IFGT A,#56        ;IF TEMPERATURE IS HIGER THAN 56 DEGREE THEN
        JSR CORR          ;ADD CORRECTION. OFFSET
;*****

```

TL/DD/12075-12


```

;*****
;
;HEX TO BCD CONVERSION
    X A,ZL
    LD A,ZL
    IFGT A,#100      ;IF TEMPERATURE IS MORE THAN 100 DEGREE THEN
    JP ERR           ;ERROR
    JSR BINBCD       ;SUBROUTINE BINARY TO BCD CONVERSION;
    LD A,BCDLO
    X A,TEMP
    LD A,BCDLO+1
    X A,TEMP+1
    RET
ERR: LD A,#00E      ;ERROR MESSAGE IS DISPLAYED
    X A,TEMP
    CLR A
    X A,TEMP+1
    RET
;*****
COMP: LD A,COMPL     ;IF THE LAST BOTH MEASUREMENTS ARE EQUAL
    SC              ;THEN DISPLAY
    SUBC A,TEMP
    IFEQ A,#0
    JP DISPLAY
    RET             ;OTHERWISE DISPLAY THE OLD VALUE
DISPLAY:LD A,TEMP
    X A,PB+2
    LD A,TEMP+1
M1: X A,PB+3
    JSR LCDDR       ;UPDATE THE DISPLAY
    JSR DEL         ;DELAY TIME
    RET
;*****
SAVE: LD A,TEMP      ;TEMPORARY SAVE
    X A,COMPL
    LD A,TEMP+1
    X A,COMPH
    RET
;*****

```

TL/DD/12075-13

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

 <p>National Semiconductor Corporation 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090 Tel: 1(800) 272-9959 TWX: (910) 339-9240</p>	<p>National Semiconductor GmbH Livny-Gargan-Str. 10 D-82256 Fürstenfeldbruck Germany Tel: (81-41) 35-0 Telex: 527849 Fax: (81-41) 35-1</p>	<p>National Semiconductor Japan Ltd. Sumitomo Chemical Engineering Center Bldg, 7F 1-7-1, Nakase, Mihama-Ku Chiba-City, Ciba Prefecture 261 Tel: (043) 299-2300 Fax: (043) 299-2500</p>	<p>National Semiconductor Hong Kong Ltd. 13th Floor, Straight Block, Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960</p>	<p>National Semicondutores Do Brazil Ltda. Rue Deputado Lacorda Franco 120-3A Sao Paulo-SP Brazil 05418-000 Tel: (55-11) 212-5066 Telex: 391-1131931 NSBR BR Fax: (55-11) 212-1181</p>	<p>National Semiconductor (Australia) Pty, Ltd. Building 16 Business Park Drive Monash Business Park Nottingham, Melbourne Victoria 3168 Australia Tel: (3) 558-9999 Fax: (3) 558-9998</p>
--	---	--	---	---	---

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.